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MCOT256064DY-	ВМ	256 x 64	Blue OLED Modul			
	Specification					
Version	n: 1			Date: 17/05/2016		
			Revision			
1	17/05/2	2016	First Release.			

Display F	Display Features		
Resolution	256 x 64		
Appearance	Blue on Black		D' HC
Logic Voltage	3V		RoHS compliant
Interface	Parallel / SPI / I <sup>2</sup> C		compliant
Module Size	60.50 x 19.00 x 1.60mm		-
Operating Temperature	-40°C ~ +80°C	Box Quantity	Weight / Display
Construction	СОТ		

<sup>\* -</sup> For full design functionality, please use this specification in conjunction with the SH1122 specification.(Provided Separately)

Display Accessories				
Part Number	Description			

Optional Variants				
Appearance	Voltage			

### **Basic Specifications**

### **Display Specifications**

1) Display Mode : Passive Matrix

2) Display Color : Monochrome with 16 Gray Scales (aght Blue)

3) Drive Duty : 1/64 Duty

### **Mechanical Specifications**

1) Outline Drawing : According to the annexed outline drawing

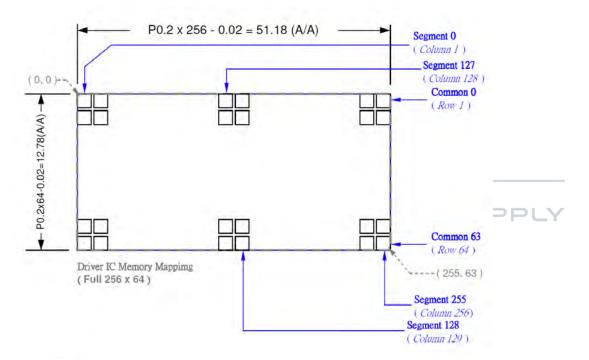
2) Number of Pixels :  $256 \times 64$ 

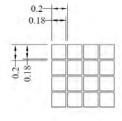
3) Module Size :  $82.50 \times 19.00 \times 1.60$  (mm)

4) Panel Size :  $60.50 \times 19.00 \times 1.60$  (mm) including "Anti-Glare Polarizer"

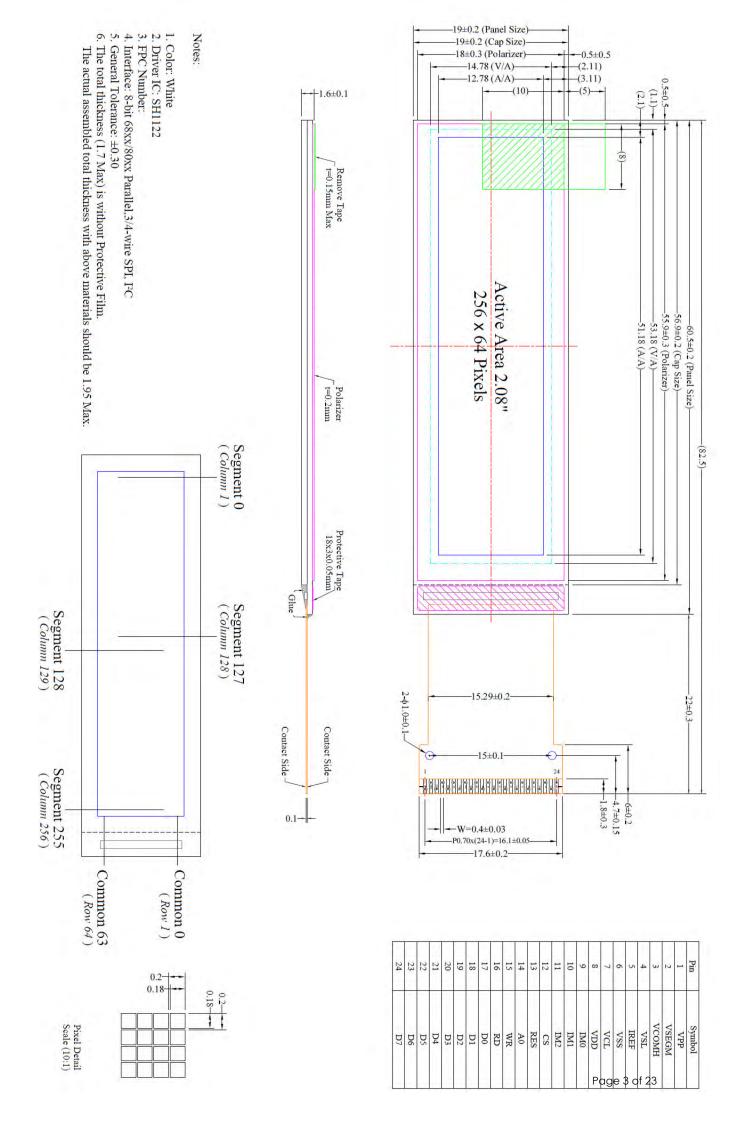
5) Active Area :  $51.18 \times 12.78$  (mm) 6) Pixel Pitch :  $0.20 \times 0.20$  (mm) 7) Pixel Size :  $0.18 \times 0.18$  (mm) 8) Weight : 3.93 (g)  $\pm 10\%$ 

### **Active Area / Memory Mapping & Pixel Construction**





Pixel Detail Scale (10:1)



### **Pin Definition**

Pin Number	Symbol	I/O	Function
Power Suppl	y		
1	VPP	Р	Power Supply for OEL Panel These are the most positive voltage supply pin of the chip. They must be connected to external source.
6	VSS	Р	Ground of Logic Circuit  This is a ground pin. It also acts as a reference for the logic pins. It must be connected to external ground.
8	VDD	Р	Power Supply for Operation This is a voltage supply pin. It must be connected to external source.
Driver			
2	VSEGM	0	Voltage Output High Level for Segment Pre-Charge  This pin is for the voltage output high level for SEG pre-charge. A capacitor should be connected between this pin and GND.
3	VCOMH	0	Voltage Output High Level for COM Signal  This pin is for the voltage output high level for COM signals. A capacitor should be connected between this pin and GND.
4	VSL	Р	Voltage Reference of Segment  This pin is segment voltage reference pin. A capacitor should be connected between this pin and GND.
5	IREF	0	Current Reference for Brightness Adjustment This pin is segment current reference pin. A resistor should be connected between this pin and GND. Set the current at 15.625µA maximum.
7	VCL	Р	Voltage Reference of Common This pin is Common voltage reference pin. This pad should be connected VSS externally.
Interface			
9 10 11	IM0 IM1 IM2	I	Communicating Protocol Select           These pins are MCU interface selection input. See the following table:           Interface mode         IM0         IM1         IM2           3-wire Serial         1         0         0           4-wire Serial         0         0         0           I <sup>2</sup> C         0         1         0           8-bit 68XX Parallel         0         0         1           8-bit 80XX Parallel         0         1         1
DESIG	CS	1	Chip Select This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled low.
13	RES	I	Power Reset for Controller and Driver This pin is reset signal input. When the pin is low, initialization of the chip is executed. Keep this pin pull high during normal operation.
14	AO	I	Data/Command Control  This pin is Data/Command control pin.  When the pin is pulled high, the input at D7~D0 is treated as display data.  When the pin is pulled low, the input at D7~D0 will be transferred to the command register.  In I²C interface, this pad serves as SA0 to distinguish the different address.  For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams.
15	WR (R/W)	I	Read/Write Select or Write  This pin is MCU interface input.  When interfacing to a 68XX-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Pull this pin to "High" for read mode and pull it to "Low" for write mode.  When 80XX interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled low and the CS# is pulled low.  When serial mode is selected, this pin must be connected to V <sub>SS</sub> .

### **Pin Definition (Continued)**

Pin Number	Symbol	I/O	Function
Interface (Continued)			
16	RD	I	Read/Write Enable or Read This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled high and the CS# is pulled low. When connecting to an 80XX-microprocessor, this pin receives the Read (RD#) signal. Data read operation is initiated when this pin is pulled low and CS# is pulled low. When serial mode is selected, this pin must be connected to V <sub>SS</sub> .
17~24	D7~D0	I/O	Host Data Input/Output Bus  These pins are 8-bit bi-directional data bus to be connected to 8-bit standard MPU data bus.  When serial mode is selected, D1 will be the serial data input pad (SI) and D0 will be the serial clock input pad (SCL). At this time, D2 to D7 are set to high impedance.  When I²C interface is selected, D1 will be the serial data input pad (SDA) and D0 will be the serial clock input pad (SCL). At this time, D2 to D7 are set to high impedance.



## Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Core Operation	$V_{DD}$	-0.3	3.6	V	1, 2
Supply Voltage for Display	V <sub>PP</sub>	0.3	14.5	i i V	1, 2
Operating Temperature	$T_OP$	-40		°C	3
Storage Temperature	$T_{STG}$	-40	85	°C	3

Note 1: All the above voltages are on the basis of " $V_{SS} = 0V$ ".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 3. "Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

Note 3: The defined temperature ranges do not include the polarizer. temperature of the polarizer should be  $80^{\circ}\text{C}$ .

Note 4:  $V_{CC}$  = 12.0V,  $T_a$  = 25°C, 50% Checkerboard.

Software configuration follows Section 4.5 Initialization.

End of lifetime is specified as 50% of initial brightness reached. The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

### Optics & Electrical Characteristics

### **Optics Characteristics**

Characteristics	Symbol	Conditions	Min	Тур	Max	Unit
Brightness	L <sub>br</sub>	Note 5	120	150	200	cd/m <sup>2</sup>
C.I.E. (Light Blue)	(x) (y)	C.I.E. 1931	0.12 0.22	0.16 0.26	0.20 0.30	
Dark Room Contrast	CR		-	>10,000:1	-	
Viewing Angle			-	Free	-	degree

<sup>\*</sup> Optical measurement taken at  $V_{\text{DD}}=3.0\text{V},\,V_{\text{CC}}=12.0\text{V}.$  Software configuration follows Section 4.5 Initialization.

#### **DC Characteristics**

Characteristics	Symbol	Conditions	Min	Тур	Max	Unit
Supply Voltage for Operation	$V_{DD}$		1.65	3.0	3.5	٧
Supply Voltage for Display	$V_{CC}$	Note 5	11.5	12.0	12.5	
High Level Input	$V_{IHC}$		$0.8 \times V_{DD}$	-	V <sub>DD</sub>	V
Low Level Input	$V_{ILC}$		$V_{SS}$		$0.2 \times V_{DD}$	V
High Level Output	V <sub>OHC</sub>	$I_{OH} = -0.5 \text{mA}$	$0.8 \times V_{DD}$	-	$V_{DD}$	V
Low Level Output	V <sub>OLC</sub>	$I_{OL} = 0.5 \text{mA}$	$V_{SS}$		$0.2 \times V_{DD}$	V
CDA low lovel output voltage	V	$V_{DD} < 2V, I_{OL} = 0.3mA$	V	-	$0.2 \times V_{DD}$	V
SDA low-level output voltage	V <sub>OLCS</sub>	$V_{DD} > 2V, I_{OL} = 0.3mA$	$V_{SS}$	-	0.4	V
Operating Current for V <sub>DD</sub>	$I_{DD}$		50	110	160	– μA
DESIGN N		Note 6	8	_16.1	20.1	mA
Operating Current for V <sub>PP</sub>	${ m I}_{\sf PP}$	Note 7	13.6	27.2	34.0	mA
		Note 8	25.7	51.4	64.3	mA
Sleep Mode Current for V <sub>DD</sub>	$I_{ extsf{DD},  extsf{SLEEP}}$		-	-	5	μA
Sleep Mode Current for V <sub>PP</sub>	${ m I}_{\sf PP,\;SLEEP}$		-		5	μA

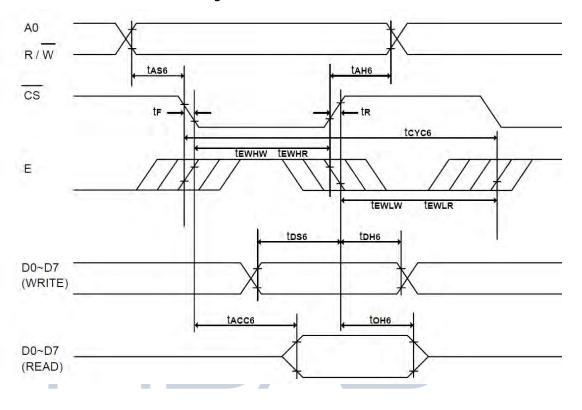
Note 5: Brightness (L<sub>br</sub>) and Supply Voltage for Display (V<sub>PP</sub>) are subject to the change of the panel characteristics and the customer's request.

Note 6:  $V_{DD}=3.0V$ ,  $V_{PP}=12.0V$ , 30% Display Area Turn on. Note 7:  $V_{DD}=3.0V$ ,  $V_{PP}=12.0V$ , 50% Display Area Turn on. Note 8:  $V_{DD}=3.0V$ ,  $V_{PP}=12.0V$ , 100% Display Area Turn on.

<sup>\*</sup> Software configuration follows Section 4.5 Initialization.

### **AC Characteristics**

6800-Series MPU Parallel Interface Timing Characteristics:



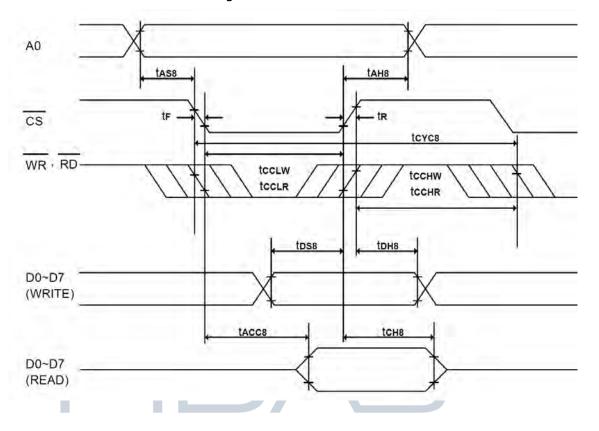
Symbol	Description	Min	Max	Unit
t <sub>cyc6</sub>	System cycle time	600	-	ns
t <sub>AS6</sub>	Address Setup Time	0	-	ns
t <sub>AH6</sub>	Address Hold Time	_ 0		ns
t <sub>DS6</sub>	Data Setup Time	80	-	ns
t <sub>DH6</sub>	Data Hold Time	30	-	ns
t <sub>CH6</sub>	Output Disable Time (C <sub>L</sub> =100pF)	20	140	ns
t <sub>ACC6</sub>	Access Time (C <sub>L</sub> =100pF)	-	280	ns
t <sub>EWHW</sub>	Enable H pulse width(Write)	200	-	ns
t <sub>EWHR</sub>	Enable H pulse width(Read)	240	-	ns
t <sub>EWLW</sub>	Enable L pulse width(Writw)	200	-	ns
t <sub>EWLR</sub>	Enable L pulse width(Read)	200	-	ns
t <sub>R</sub>	Rise Time	-	30	ns
t <sub>F</sub>	Fall Time	-	30	ns

<sup>\* (</sup>VDD -VSS = 1.65V-3.5V, TA = +25°C)

Symbol	Description	Min	Max	Unit
t <sub>cyc6</sub>	System cycle time	300	-	ns
t <sub>AS6</sub>	Address Setup Time	0	-	ns
t <sub>AH6</sub>	Address Hold Time	0	-	ns
t <sub>DS6</sub>	Data Setup Time	40	_	ns
t <sub>DH6</sub>	Data Hold Time	15	-	ns
t <sub>CH6</sub>	Output Disable Time (C <sub>L</sub> =100pF)	10	70	ns
t <sub>ACC6</sub>	Access Time (C <sub>L</sub> =100pF)	-	140	ns
t <sub>EWHW</sub>	Enable H pulse width(Write)	100	-	ns
t <sub>EWHR</sub>	Enable H pulse width(Read)	120	-	ns
t <sub>EWLW</sub>	Enable L pulse width(Writw)	100	-	ns
t <sub>EWLR</sub>	Enable L pulse width(Read)	100	_	ns
t <sub>R</sub>	Rise Time	-	15	ns
t <sub>F</sub>	Fall Time	-	15	ns



## 8080-Series MPU Parallel Interface Timing Characteristics:



Symbol	Description	Min	Max	Unit
t <sub>cyc8</sub>	System cycle time	600	-	ns
t <sub>AS8</sub>	Address Setup Time	0	-	ns
t <sub>AH8</sub>	Address Hold Time	0	-	ns
E t <sub>DS8</sub>	Data Setup Time NUFACTURE •	<b>580</b> F	PLY	ns
t <sub>DH8</sub>	Data Hold Time	30	-	ns
t <sub>CH8</sub>	Output Disable Time (C <sub>L</sub> =100pF)	20	140	ns
t <sub>ACC8</sub>	Access Time (C <sub>L</sub> =100pF)	-	280	ns
t <sub>CCLW</sub>	Control L pulse width(WR)	200	-	ns
$t_{CCLR}$	Control L pulse width(RD)	240	-	ns
t <sub>cchw</sub>	Control H pulse width(WR)	200	-	ns
t <sub>CCHR</sub>	Control H pulse width(RD)	200	-	ns
$t_R$	Rise Time	-	30	ns
t <sub>F</sub>	Fall Time	-	30	ns

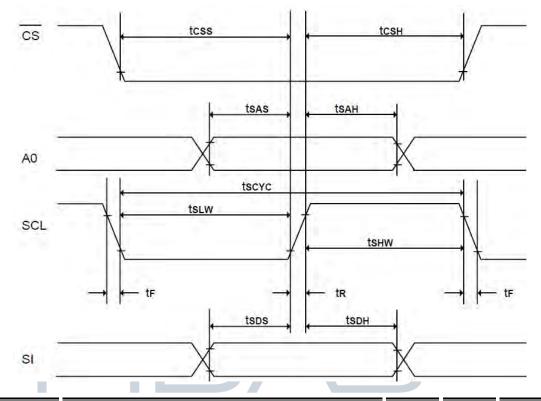
<sup>\* (</sup>VDD -VSS = 1.65V-3.5V, TA = +25°C)

Symbol	Description	Min	Max	Unit
t <sub>cyc8</sub>	System cycle time	300	-	ns
t <sub>AS8</sub>	Address Setup Time	0	-	ns
t <sub>AH8</sub>	Address Hold Time	0	-	ns
t <sub>DS8</sub>	Data Setup Time	40	-	ns
t <sub>DH8</sub>	Data Hold Time	15	-	ns
t <sub>CH8</sub>	Output Disable Time (C <sub>L</sub> =100pF)	10	70	ns
t <sub>ACC8</sub>	Access Time (C <sub>L</sub> =100pF)	-	140	ns
t <sub>CCLW</sub>	Control L pulse width(WR)	100	-	ns
t <sub>CCLR</sub>	Control L pulse width(RD)	120	-	ns
t <sub>CCHW</sub>	Control H pulse width(WR)	100	-	ns
t <sub>CCHR</sub>	Control H pulse width(RD)	100	-	ns
t <sub>R</sub>	Rise Time	-	15	ns
t <sub>F</sub>	Fall Time	-	15	ns

<sup>\* (</sup>VDD -VSS = 2.4V-3.5V, TA = +25°C)



# Serial Interface Timing Characteristics: (4-wire SPI)



Symbol	Description	Min	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	500	-	ns
$t_{SAS}$	Address Setup Time	300	-	ns
 t <sub>SAH</sub>	Address Hold Time	300	-	_ ns
$t_{ extsf{SDS}}$	Write Data Setup Time	200	-	ns
$t_{SDH}$	Write Data Hold Time	200		ns
t <sub>CSS</sub>	CS Setup Time	240	-	ns
t <sub>CSH</sub>	CS Hold Time	120	-	ns
$t_{SHW}$	Serial Clock H pulse Time	200	-	ns
$t_{SLW}$	Serial Clock L pulse Time	200	-	ns
$t_{R}$	Rise Time	-	30	ns
t <sub>F</sub>	Fall Time	-	30	ns

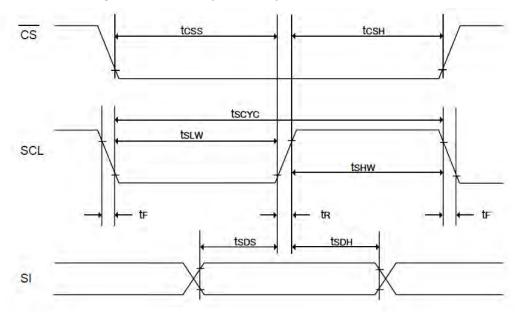
<sup>\* (</sup>VDD -VSS = 1.65V ~ 3.5V, TA = 25°C)

Symbol	Description	Min	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	250	-	ns
$t_{SAS}$	Address Setup Time	150	-	ns
t <sub>SAH</sub>	Address Hold Time	150	-	ns
$t_{ extsf{SDS}}$	Write Data Setup Time	100	-	ns
$t_{SDH}$	Write Data Hold Time	100	-	ns
$t_{CSS}$	CS Setup Time	120	-	ns
t <sub>CSH</sub>	CS Hold Time	60	-	ns
$t_{SHW}$	Serial Clock H pulse Time	100	-	ns
$t_{\scriptscriptstyleSLW}$	Serial Clock L pulse Time	100	-	ns
t <sub>R</sub>	Rise Time	-	15	ns
t <sub>F</sub>	Fall Time	-	15	ns

<sup>\* (</sup>VDD -VSS = 2.4V ~ 3.5V, TA = 25°C)



## 3.3.4 Serial Interface Timing Characteristics: (3-wire SPI)



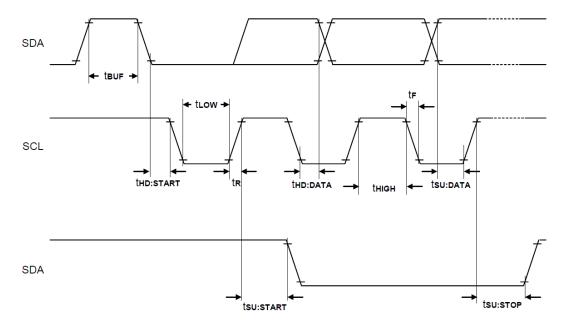
Symbol	Description	Min	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	500	-	ns
t <sub>SDS</sub>	Write Data Setup Time	200	-	ns
t <sub>SDH</sub>	Write Data Hold Time	200	-	ns
t <sub>CSS</sub>	CS Setup Time	240	-	ns
t <sub>CSH</sub>	CS Hold Time	120	-	ns
$t_{SHW}$	Serial Clock H pulse Time	200	-	ns
t <sub>SLW</sub>	Serial Clock L pulse Time	200	-	ns
=St <sub>R</sub> Gr	Rise Time ANUEACTURE	SUE	30	/ ns
t <sub>F</sub>	Fall Time	-	30	ns

<sup>\* (</sup>VDD -VSS = 1.65V ~ 3.5V, TA = 25°C)

Symbol	Description	Min	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	250	-	ns
$t_{ extsf{SDS}}$	Write Data Setup Time	100	-	ns
$t_{SDH}$	Write Data Hold Time	100	-	ns
$t_{CSS}$	CS Setup Time	120	-	ns
t <sub>CSH</sub>	CS Hold Time	60	-	ns
$t_{SHW}$	Serial Clock H pulse Time	100	-	ns
$t_{SLW}$	Serial Clock L pulse Time	100	-	ns
t <sub>R</sub>	Rise Time	-	15	ns
t <sub>F</sub>	Fall Time	-	15	ns

<sup>\* (</sup>VDD -VSS = 2.4V ~ 3.5V, TA = 25°C)

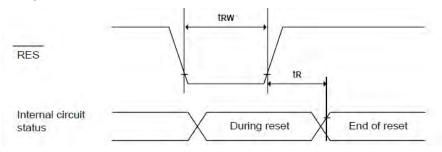
# $\ensuremath{\mathrm{I}}^2\ensuremath{\mathrm{C}}$ Interface Timing Characteristics:



	Symbol	Description	Min	Max	Unit
	f <sub>SCL</sub>	SCL clock frequency	DC	400	kHz
	T <sub>LOW</sub>	SCL Clock L pulse Time	1.3	-	μ <b>S</b>
	T <sub>HIGH</sub>	SCL Clock H pulse Time	0.6		μ <b>S</b>
	T <sub>SU: DATA</sub>	Data Setup Time	100	-	ns
	T <sub>HU: DATA</sub>	Data Hold Time	0	0.9	μ <b>S</b>
	$T_R$	SCL · SDA rise Time	20+0.1Cb	300	ns
	ESTGI	SCL SDA fall Time	20+0.1Cb	J =300 L	/ ns
	Cb	Capacity load on each bus line	-	400	pF
	T <sub>SU: START</sub>	Setup Time for re-START	0.6	-	μ <b>S</b>
	T <sub>HU: START</sub>	START Hold Time	0.6	-	μ <b>S</b>
	T <sub>SU: STOP</sub>	Setup Time for STOP	0.6	-	μ <b>S</b>
	$T_{BUF}$	Bus free time between STOP and START condition	1.3	-	μ <b>S</b>

<sup>\* (</sup>VDD -VSS = 1.65V ~ 3.5V, TA = 25°C)

### 3.3.6 Reset Timing Characteristics:



Symbol	Description	Min	Max	Unit
$t_R$	Reset Time	-	2	μ <b>S</b>
t <sub>RW</sub>	Reset low pulse Time	10	-	μ <b>S</b>

<sup>\* (</sup>VDD -VSS = 1.65V ~ 3.5V, TA = 25°C)

Symbol	Description	Min	Max	Unit
t <sub>R</sub>	Reset Time	-	1	μ <b>S</b>
t <sub>RW</sub>	Reset low pulse Time	5	-	μ <b>S</b>

<sup>\* (</sup>VDD -VSS = 2.4V ~ 3.5V, TA = 25°C)

# DISPLAYS

### Functional Specification

#### **Commands**

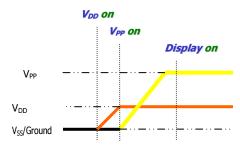
Refer to the Technical Manual for the SH1122

### **Power down and Power up Sequence**

To protect OEL panel and extend the panel life time, the driver IC power up/down routine should include a delay period between high voltage and low voltage power sources during turn on/off. It gives the OEL panel enough time to complete the action of charge and discharge before/after the operation.

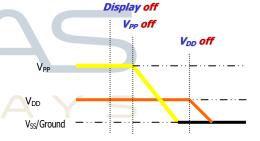


- 1. Power up  $V_{\text{DD}}$
- 2. Send Display off command
- 3. Initialization
- 4. Clear Screen
- 5. Power up  $V_{PP}$
- 6. Delay 200ms (When  $V_{PP}$  is stable)
- 7. Send Display on command



### Power down Sequence:

- 1. Send Display off command
- 2. Power down V<sub>PP</sub>
- 3. Delay 100ms
  (When V<sub>PP</sub> is reach 0 and panel is completely discharges)
- 4. Power down V<sub>DD</sub>



#### Note 9:

- 1) Since an ESD protection circuit is connected between  $V_{DD}$  and  $V_{PP}$  inside the driver IC,  $V_{PP}$  becomes lower than  $V_{DD}$  whenever  $V_{PP}$  is OFF.
- - 3) Power Pins  $(V_{DD}, V_{PP})$  can never be pulled to ground under any circumstance.
  - 4)  $V_{DD}$  should not be power down before  $V_{PP}$  power down.

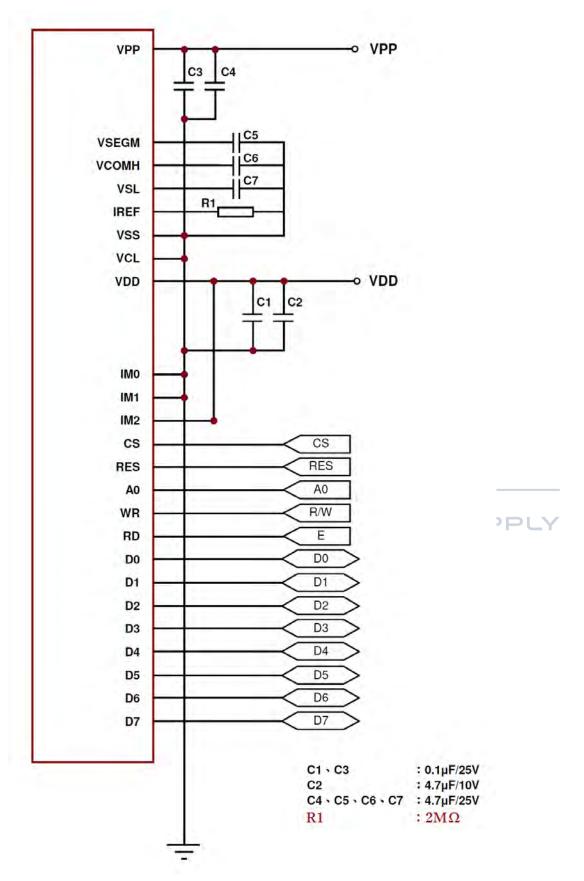
#### **Reset Circuit**

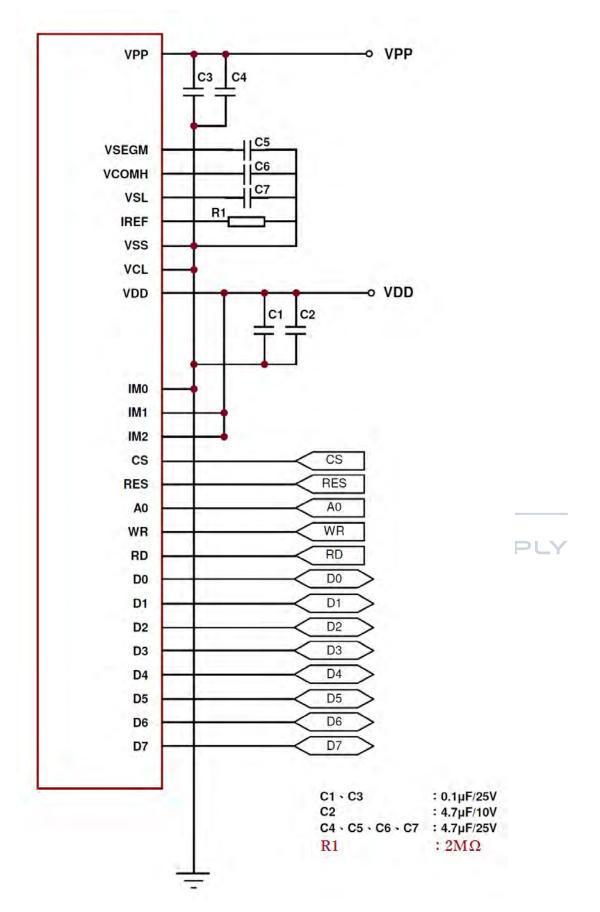
When RES# input is low, the chip is initialized with the following status:

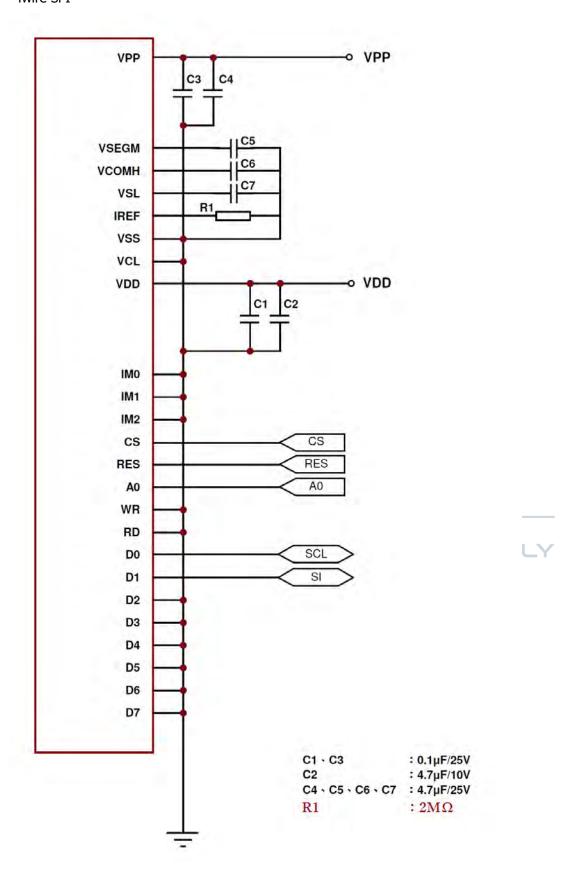
- 1. Display is OFF. Common and Segment are in high impedance state.
- 2.  $256 \times 64$  Display Mode
- 3. Normal segment and display data column and row address mapping (SEG0 mapped to column address 00h and COM0 mapped to row address 00h)
- 4. Shift register data clear in serial interface.
- 5. Display start line is set at display RAM address 00H
- 6. Column address counter is set at 0
- 7. Normal scanning direction of the Common outputs
- 8. Contrast control register is set at 80H
- 9. Internal DC-DC is selected.

### **Application circuit**

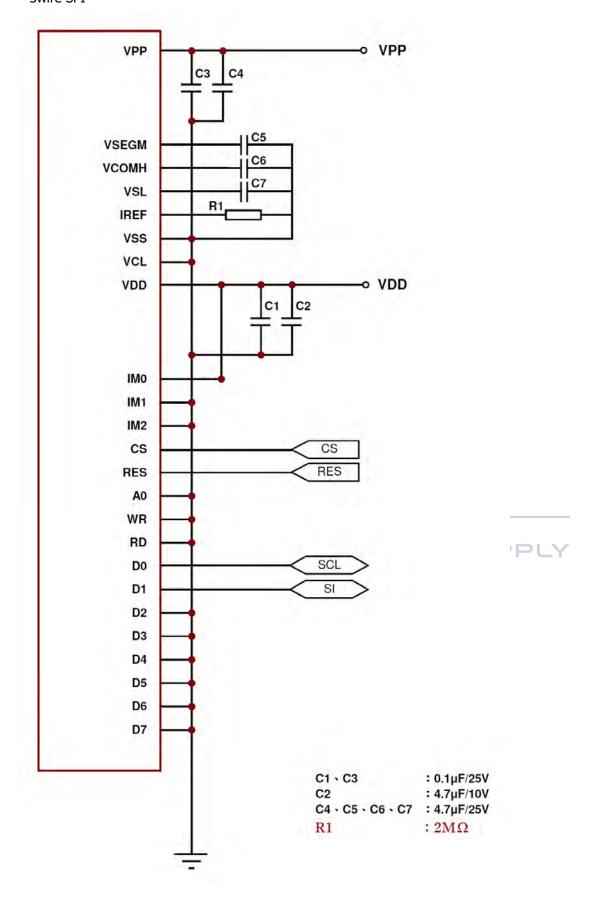
6800-Series MPU Parallel Interface



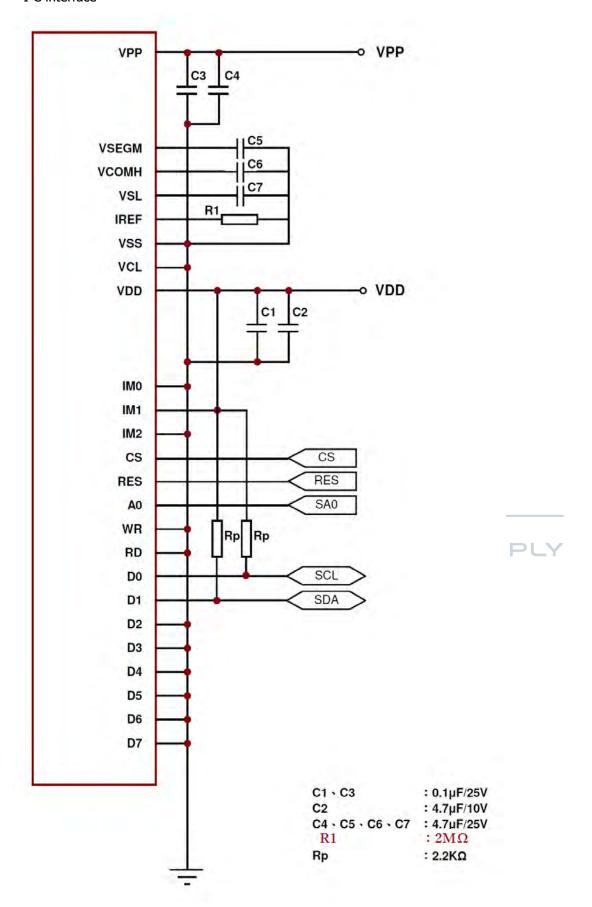




3wire SPI



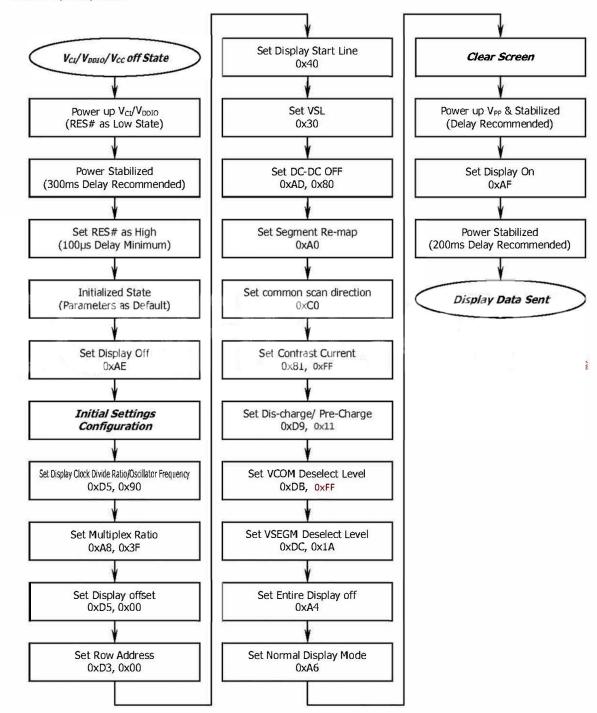
### I<sup>2</sup>C interface



### 4.5 Actual Application Example

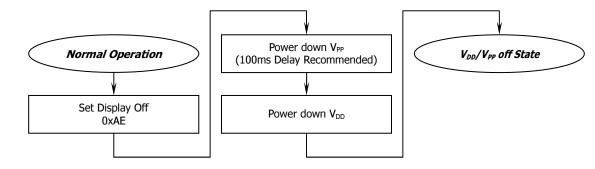
Command usage and explanation of an actual example

<Power up Sequence>



If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.

### <Power down Sequence>



### <Entering Sleep Mode>

